## AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1-14. (canceled)

15. (currently amended) An article of manufacture, comprising:

at least two integrated circuit (IC) packages in stacked relation to each other, each of the IC packages including:

a substrate;

an IC mounted on a first surface of the substrate;

a ground plane formed on an opposite surface of the substrate from the first surface on which the IC is mounted; and

a coverlay formed of an organic material and laminated on the first surface of the substrate and having at least one opening formed by photolithography; and

at least one conductive connection formed through one of the coverlays and connecting one of the ICs to another of the ICs;

wherein each IC is positioned in an opening of a respective one of the coverlays, the opening formed by photolithography, all of said each IC being in said opening of said respective one of the coverlays.

16. (canceled)

17. (original) The article of manufacture of claim 15, wherein the coverlays are of a flexible material.

18. (original) The article of manufacture of claim 17, wherein the substrates are of a flexible material.

19. (currently amended) An apparatus comprising:

a stacked integrated circuit (IC) package which includes:

a first substrate;

a first IC mounted on a first surface of the first substrate;

a first ground plane formed on an opposite surface of the first substrate from the first surface on which the first IC is mounted;

a first coverlay formed of an organic material and laminated on the first surface of the first substrate and having at least one opening formed by photolithography;

a second substrate positioned in stacked fashion on the first coverlay;

a second IC mounted on a first surface of the second substrate;

a second ground plane formed on an opposite surface of the second substrate from the first surface on which the second IC is mounted;

a second coverlay laminated on the first surface of the second substrate and having at least one opening formed by photolithography; and

at least one conductive connection connecting the first IC to the second IC and passing through at least one opening in the first coverlay; and

a communication device coupled to at least one of the first IC and the second IC;

wherein:

the first IC is positioned in an opening formed by photolithography in the first coverlay, all of the first IC being in said opening formed by photolithography in the first coverlay; and

the second IC is positioned in an opening formed by photolithography in the second coverlay, all of the second IC being in said opening formed by photolithography in the second coverlay.

20. (canceled)

21. (original) The apparatus of claim 19, wherein the first and second coverlays are of a flexible material.

22. (original) The apparatus of claim 21, wherein the first and second substrates are of a flexible material.

23-33. (canceled)

34. (currently amended) An article of manufacture, comprising:

at least two integrated circuit (IC) packages in stacked relation to each other, each of the IC packages including:

a substrate;

an IC mounted on a first surface of the substrate;

a ground plane formed on an opposite surface of the substrate from the first surface on which the IC is mounted; and

a coverlay of a flexible organic material laminated on the first surface of the substrate and having at least one opening formed in the coverlay; and

at least one conductive connection formed through one of the coverlays and connecting one of the ICs to another of the ICs;

wherein each IC is positioned in an opening of a respective one of the coverlays, all of said each IC being in said opening of said respective one of the coverlays.

35. (canceled)

36. (original) The article of manufacture of claim 34, wherein the substrates are of a flexible material.

37. (currently amended) An apparatus comprising:

a stacked integrated circuit (IC) package which includes:

a first substrate;

a first IC mounted on a first surface of the first substrate;

a first ground plane formed on an opposite surface of the first substrate from the first surface on which the first IC is mounted;

a first coverlay of a flexible organic material laminated on the first surface of the first substrate and having at least one opening formed in the first coverlay;

a second substrate positioned in stacked fashion on the first coverlay;

a second IC mounted on a first surface of the second substrate;

a second ground plane formed on an opposite surface of the second substrate from the first surface on which the second IC is mounted;

a second coverlay of a flexible organic material laminated on the first surface of the second substrate and having at least one opening formed in the second coverlay; and

at least one conductive connection connecting the first IC to the second IC and passing through at least one opening in the first coverlay; and

a communication device coupled to at least one of the first IC and the second IC;

wherein:

the first IC is positioned in an opening in the first coverlay, all of the first IC being in said opening in the first coverlay; and

the second IC is positioned in an opening in the second coverlay, all of the second IC being in said opening in the second coverlay.

38. (canceled)

39. (original) The apparatus of claim 37, wherein the first and second substrates are of a flexible material.

40. (new) The article of manufacture of claim 15, further comprising:

a solder mask layer which covers the ground plane.

41. (new) The apparatus of claim 19, further comprising:

a first solder mask layer which covers the first ground plane; and

a second solder mask layer which covers the second ground plane.

42. (new) The article of manufacture of claim 34, further comprising:

a solder mask layer which covers the ground plane.

43. (new) The apparatus of claim 37, further comprising:

a first solder mask layer which covers the first ground plane; and

a second solder mask layer which covers the second ground plane.